

| L Number | Hits | Search Text | DB | Time stamp |
|----------|---------|--|--------------------|------------------|
| 1 | 196866 | mold | USPAT; US-PGPUB | 2004/03/18 16:02 |
| 2 | 295480 | insert | USPAT; US-PGPUB | 2004/03/18 15:55 |
| 3 | 422304 | injection | USPAT; US-PGPUB | 2004/03/18 15:55 |
| 4 | 138097 | wafer | USPAT; US-PGPUB | 2004/03/18 16:01 |
| 5 | 83359 | masking | USPAT; US-PGPUB | 2004/03/18 15:55 |
| 6 | 233471 | etch\$3 | USPAT; US-PGPUB | 2004/03/18 15:55 |
| 7 | 273061 | mask\$3 | USPAT; US-PGPUB | 2004/03/18 15:55 |
| 8 | 523095 | mold\$3 | USPAT; US-PGPUB | 2004/03/18 15:56 |
| 9 | 4017 | wafer and etch\$3 and mask\$3 and mold\$3 | USPAT; US-PGPUB | 2004/03/18 16:03 |
| 10 | 867 | (wafer and etch\$3 and mask\$3 and mold\$3) and 438/\$.ccls. | USPAT; US-PGPUB | 2004/03/18 16:48 |
| 11 | 622457 | wafer substrate | USPAT; US-PGPUB | 2004/03/18 16:01 |
| 12 | 100827 | etch\$3 with (wafer substrate) | USPAT; US-PGPUB | 2004/03/18 16:02 |
| 13 | 236451 | mold | USPAT; US-PGPUB | 2004/03/18 16:02 |
| 14 | 5283 | mask\$3 and mold\$3 and (etch\$3 with (wafer substrate)) | USPAT; US-PGPUB | 2004/03/18 16:52 |
| 15 | 867 | ((wafer and etch\$3 and mask\$3 and mold\$3) and 438/\$.ccls.) and 438/\$.ccls. | USPAT; US-PGPUB | 2004/03/18 16:52 |
| 16 | 1506398 | metal conductive | USPAT; US-PGPUB | 2004/03/18 16:04 |
| 17 | 76933 | mold\$3 with (metal conductive) | USPAT; US-PGPUB | 2004/03/18 16:05 |
| 18 | 209 | ((((wafer and etch\$3 and mask\$3 and mold\$3) and 438/\$.ccls.) and 438/\$.ccls.) and (mold\$3 with (metal conductive))) | USPAT; US-PGPUB | 2004/03/18 16:47 |
| 19 | 548771 | carrier | USPAT; US-PGPUB | 2004/03/18 16:06 |
| 20 | 64 | (((((wafer and etch\$3 and mask\$3 and mold\$3) and 438/\$.ccls.) and 438/\$.ccls.) and (mold\$3 with (metal conductive)))) and carrier | USPAT; US-PGPUB | 2004/03/18 16:07 |
| 21 | 145 | (((((wafer and etch\$3 and mask\$3 and mold\$3) and 438/\$.ccls.) and 438/\$.ccls.) and (mold\$3 with (metal conductive)))) not (((((wafer and etch\$3 and mask\$3 and mold\$3) and 438/\$.ccls.) and 438/\$.ccls.) and (mold\$3 with (metal conductive)))) and carrier) | USPAT; US-PGPUB | 2004/03/18 16:30 |
| 22 | 1256 | ((mask\$3 and mold\$3 and (etch\$3 with (wafer substrate))) and (mold\$3 with (metal conductive))) | USPAT; US-PGPUB | 2004/03/18 16:52 |
| 23 | 230 | ((mask\$3 and mold\$3 and (etch\$3 with (wafer substrate))) and (mold\$3 with (metal conductive))) and 438/\$.ccls. | USPAT; US-PGPUB | 2004/03/18 17:00 |
| 24 | 97 | ((((mask\$3 and mold\$3 and (etch\$3 with (wafer substrate))) and (mold\$3 with (metal conductive))) and 438/\$.ccls.) not (((((wafer and etch\$3 and mask\$3 and mold\$3) and 438/\$.ccls.) and 438/\$.ccls.) and (mold\$3 with (metal conductive)))) | USPAT; US-PGPUB | 2004/03/18 16:53 |
| 25 | 111 | ((mask\$3 and mold\$3 and (etch\$3 with (wafer substrate))) and (mold\$3 with (metal conductive))) and 216/\$.ccls. | USPAT; US-PGPUB | 2004/03/18 17:00 |